Connector for SD Memory Card

SCDA Series



Compact low-profile type with highly reliable contact structure.

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For Memory Stick Micro™

Combine Type

For W-SIM



Typical Specifications

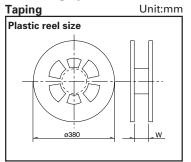
Items			Specifications			
	Applicable media		SD Memory Card/ MultiMediaCard™			
Churchin	Mounting type		Surface mounting type			
Structure	Mounting style		Standard mount/Reverse mount			
	Media ejection structure		Push-push type			
Performance	Operating temperature range		−25°C to +60°C			
	Voltage proof		100V AC 1minute			
	Insulation resistance (Initial)		1,000MΩ min.			
	Contact resistance (Initial)	Connector contacts	100mΩ max.			
		Detection switch	500mΩ max.			
	Insertion and removal cycle		10,000cycles			

Product Line

Media ejection structure	Mounting style	Features	Stand-off (mm)	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	Inner tail, card eject stroke 5mm	0	Taping	SCDA9A0400	1
		Inner tail, card eject stroke 8mm			SCDA8A0201	2
		Outer tail, card eject stroke 8mm			SCDA7A0101	3
			1.5		SCDA7A0200	4
			1.8		SCDA7A1201	5
	Reverse mount	Outortoil	0		SCDAAA0100	6
		Outer tall	Outer tail 1.8		SCDAAA0601	7



Packing Specifications



Product	Number of packages (pcs.)			Reel width	Tape width	Export package		
No.	1 reel	1 case /Japan	1 case /export packing	W (mm)	(mm)	measurements (mm)		
SCDA7A0101	400	800	1,600	45.5				
SCDA7A0200	250	500	1,000		44	403×403×249		
SCDA7A1201	300	600	1,200					
SCDA8A0201	400	800	1,600					
SCDA9A0400								
SCDAAA0100	500	1,000	2,000					
SCDAAA0601	300	600	1,200					

Note

Please place purchase orders per minimum order unit N (integer).

Unit:mm

SD Memory Card For microSD™

Card

For

8pins

Memory

Stick Micro™

Combine Type

For

W-SIM

SIM Card

Dimensions

Standard mount (Inner tail)

PC board mounting hole dimensions No. Style (Viewed from the mounting face side) Stand-off 0mm Card eject stroke 5mm Circuit Diagram for Detect SW No.10:Card Detect SW Recommended P.C.B layout Insertion Card=ON (Mounting face side) →Normal=OFF No.6:GND No.11:GND Card Detect SW ZZZZZ LAND ☐ NO PART AREA

■ NO PATTERN AREA No.12: Write Protect Detect SW Write enable=ON Write protected=OFF →Normal=OFF (No Card insertion) NO PATTERN EXPOSE AREA No.13,14:GND (Write Protect of Detect SW) 3.4 max. 15.4 min. Connector center 11.1 min. 7.4 min. 28.2 min. NO.10 Card detect switch NO.11GND 1 NO.1 NO.9 9.9 min. iiiiii NO.12 Write protect 2-01 2-ø1.3 Detect Switch NO.14GND NO.13GND Card cente (0.4) 6 7.6 9.2 <u>10 max.</u> 12.4 Stand-off 0mm Card eject stroke 8mm No.10 Card detect No.11 Common(Vss) No.12 Write protect detect switch



Land area
Pattern prohibition area

Center line of positioning bosses



0.2 (Center line of positioning bosses)

Write enable = ON

→Normal = OFF (No Card insertion)

Write protected = OFF

(11.97)

No.10: CardDetect SW No.11: Common(Vss)

Circuit Diagram for Detect SW

2

Connector

(0.82),

Dimensions Standard mount

Unit:mm

For SD Memory Card

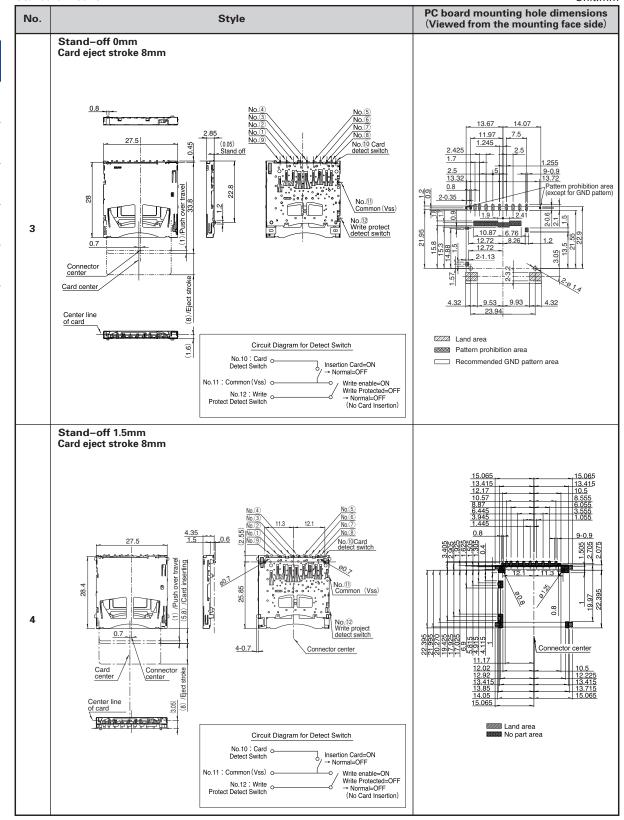
For microSD™ Card

For SIM Card 8pins

For Memory Stick Micro™

Combine Type

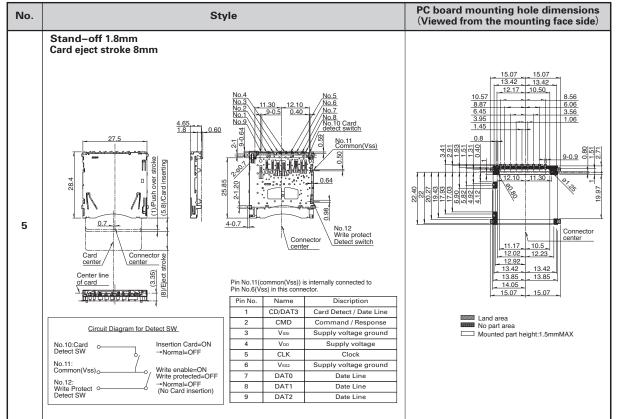
For W-SIM





Dimensions

Reverse mount Unit:mm





For microSD™ Card

For SIM Card 8pins

For Memory Stick Micro™

Combine Type

For W-SIM



Dimensions

Stand-off 0mm

No.

Reverse mount Unit:mm

For SD Memory Card

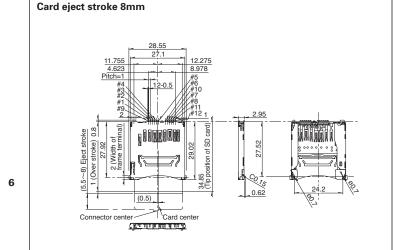
For microSD™ Card

For SIM Card 8pins

For Memory Stick Micro™

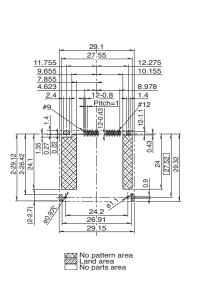
Combine Type

For W-SIM



Style

	Pin No. Name 1 CD/DAT3		Discription				
			Card Detect / Date Line				
	2	CMD	Command / Response				
	3	Vssi	Supply voltage ground				
	4 VDD 5 CLK 6 Vss2		Supply voltage				
			Clock				
FF			Supply voltage ground				
n)	7	DAT0	Date Line				
""/	8	DAT1	Date Line				
	9	DAT2	Date Line				



PC board mounting hole dimensions

(Viewed from the mounting face side)

Stand-off 1.8mm Card eject stroke 8mm

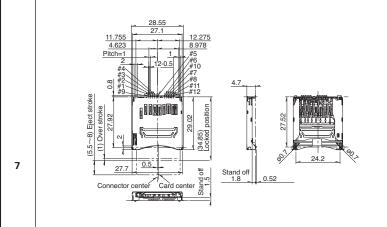
No.10: Card Detect Switch

No.6: Common (Vss)

No.11: Common

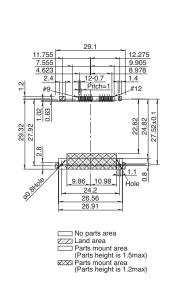
No.12: Write ect Detect Switch

Circuit Diagram for Detect Switch



Circui	t Diagram for Detect Switch
No.10: Card Detect Switch	O Insertion Card=ON → Normal=OFF
No.6: Common (Vss) No.11: Common No.12: Write Protect Detect Switch	O Write enable=ON Write Protected=FF (No Card Insertion)

Pin No.	Name	Discription			
1	CD/DAT3	Card Detect / Date Line			
2	CMD	Command / Response			
3	Vssı	Supply voltage ground			
4	V _{DD}	Supply voltage			
5	CLK	Clock			
6	Vss2	Supply voltage ground			
7	DAT0	Date Line			
8	DAT1	Date Line			
9	DAT2	Date Line			
		•			





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List of Varieties

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For Memory Stick Micro™

Combine Type

For W-SIM

Applicable media	Product No.	Photo	Media ejection structure	Mounting style	Features	Stand-off (mm)	Auto motive use	Page
	SCDA9A0400			Standard mount	Inner tail Card eject stroke 5mm	0	_	
	SCDA8A0201				Inner tail Card eject stroke 8mm			
	SCDA7A0101						0	
SD Memory Card	SCDA7A0200				Card eject stroke	1.5		527
Multi-MediaCard™	SCDA7A1201	1			8mm	1.8		321
	SCDAAA0100	California,	Push-push type	Reverse mount	Outer tail	0		
	SCDAAA0601					1.8		
	SCHA4B0100			Standard mount	With switch	0	0	
	SCHA4B0400				With switches and fly-out protection.		_	532
	SCHA5B0200			Reverse mount	With switch		0	
microSD™	SCHB1A0205		Manual insertion/ removal	Standard mount	Hinge cover type Without switch			535
Card	SCHB1B0100	1000			Hinge cover type With switch			
	SCHD1A0101				Header type		_	537
	SCHD3A0100							
	SCHH1D0100				Adapter			539

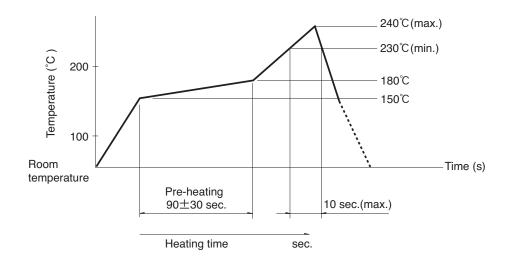
Note

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Soldering Conditions

Example of Reflow Soldering Condition (Reference)

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple 0.1 to 0.2 φ CA (K) or CC (T) at soldering portion.
- 3. Temperature profile



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Please refer to each product's specification sheet to confirm temperature profile.

Cautions for using this product

- 1. Connector hamdling precautions
- (1) Safeguard the connector assembly against flux penetration from its top side.
- (2) This product is designed on the assumption that they will not be washed after soldering.
- If youwash it, it may be cause deterioration of mechanically and electrically.
- If washing is necessary, pleasemake contact with us beforehand.
- 2. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformayion or electrical degradation to occur depending on the conditions.

Caution is therefore required.

- 3. When soldering, do not use water soluble flux because this may corrode the product.
- 4.regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.
- 5.As P.W.B. warping may alter characteristics, please take this into consideration when designing pattern and layout.
- 6.Please do not solder at the ejector pushing position.
- 7.To prevent contact disturbance by the sulfuration or oxidation of the conyact and terminal, and deterioration of solder ability by thin film on the terminal, please note following.
- Storage in the atmosphere of high temperature at 60 degrees or more, high humidity, corrosive gases such as sulfur or chlorinate gas, and excessive piling up of the carton boxes shall be avoided.
- Connectors shall be stored as the package not opened and in the normal temperature and normal humidity, and the connectors shall be used preferably within 3 months, at least within 6 months.
- When the connectors are stored after opening the package, the connectors shall be sealed with a polyethylene bag
 etc. and stored in dark and cool place, avoiding direct sunlight. Bag etc. and stored in dark and cool place, avoiding
 direct sunlight. The connectors shall be used as soon as possible.
- 8.Don't push or hold down the metal cover of the connector, otherwise there is a possibolity that the card would not be ejected or influences to other function.
- 9.Please attention following items to prevent connector from miss operation, such as bounding caused by ON/OFF switching and chattering by vibration.
- · Repeated reading/writing.
- Establish delay time-recommended 400msec min.
- · Establish CR accumulation circuit.
- 10. This product does not operate normally when the card which does not conform to the specification is used occasionally.